

# AM7334N-T1-PF-VB Datasheet N-Channel 30-V (D-S) MOSFET

| V <sub>DS</sub>                              | 30 | V  |
|--|----|----|
| R <sub>DS(on),typ</sub> V <sub>GS</sub> =10V | 13 | mΩ |
| RDS(on),typ VGS=4.5V                         | 19 | mΩ |
| ID   | 30 | Α  |

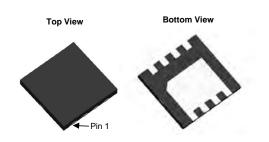
## **FEATURES**

- · Halogen-free
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

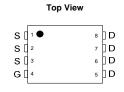


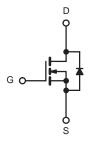
## **APPLICATIONS**

- DC/DC Conversion
  Low-Side Switch
- Notebook PC
- Gaming



DFN 3x3 EP





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATIN                              | 1A - 23 C              |                                   |                      | 1    |  |
|---|------------------------|-----------------------------------|----------------------|------|--|
| Parameter   |                        | Symbol                            | Limit                | Unit |  |
| Drain-Source Voltage                                |                        | $V_{DS}$                          | 30                   | V    |  |
| Gate-Source Voltage                                 |                        | $V_{GS}$                          | ± 20                 | V    |  |
|   | T <sub>C</sub> = 25 °C |                                   | 30                   |      |  |
| Continuous Drain Current (T <sub>.I</sub> = 150 °C) | T <sub>C</sub> = 70 °C | l <sub>D</sub>                    | 20                   |      |  |
| Continuous Drain Current (1) = 130 G)               | T <sub>A</sub> = 25 °C | ا <sup>ن</sup> [                  | 21.5 <sup>b, c</sup> |      |  |
|   | T <sub>A</sub> = 70 °C | 1                                 | 17.1 <sup>b, c</sup> | A    |  |
| Pulsed Drain Current                                |                        | I <sub>DM</sub>                   | 100                  |      |  |
| Continuous Source-Drain Diode Current               | T <sub>C</sub> = 25 °C | I <sub>S</sub>                    | 13                   |      |  |
|   | T <sub>A</sub> = 25 °C | ] 'S                              | 3.1 <sup>b, c</sup>  |      |  |
| Single Pulse Avalanche Current                      | L = 0.1 mH             | I <sub>AS</sub>                   | 10                   |      |  |
| Avalanche Energy                                    | L = 0.111111           | E <sub>AS</sub>                   | 5                    | mJ   |  |
| Maximum Power Dissipation                           | T <sub>C</sub> = 25 °C |                                   | 60                   |      |  |
|   | T <sub>C</sub> = 70 °C | $P_{D}$                           | 30                   | W    |  |
|   | T <sub>A</sub> = 25 °C | 1 'D                              | 3.7 <sup>b, c</sup>  | VV   |  |
|   | T <sub>A</sub> = 70 °C | 1                                 | 2.4 <sup>b, c</sup>  |      |  |
| Operating Junction and Storage Temperature Range    |                        | T <sub>J</sub> , T <sub>stq</sub> | - 55 to 150          | °C   |  |

| THERMAL RESISTANCE RATINGS                  |              |                   |         |         |        |  |
|---|--------------|-------------------|---------|---------|--------|--|
| Parameter                                   |              | Symbol            | Typical | Maximum | Unit   |  |
| Maximum Junction-to-Ambient <sup>b, d</sup> | t ≤ 10 s     | R <sub>thJA</sub> | 27      | 34      | °C/W   |  |
| Maximum Junction-to-Foot (Drain)            | Steady State | $R_{thJF}$        | 6       | 7.5     | C/ V V |  |

#### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 85 °C/W.



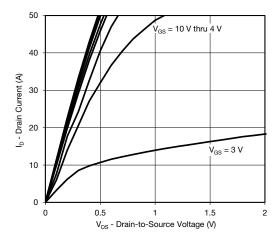
| Parameter                                     | Symbol                           | Test Conditions  | Min. | Тур.  | Max.  | Unit        |  |
|---|----------------------------------|--|------|-------|-------|-------------|--|
| Static  |                                  |  |      | •     |       |             |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>                  | $V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$   | 30   |       |       | V           |  |
| V <sub>DS</sub> Temperature Coefficient       | ΔV <sub>DS</sub> /T <sub>J</sub> | J 250A   |      | 27    |       | mV/°C       |  |
| V <sub>GS(th)</sub> Temperature Coefficient   | $\Delta V_{GS(th)}/T_J$          | - I <sub>D</sub> = 250 μA  |      | - 5.6 |       |             |  |
| Gate-Source Threshold Voltage                 | V <sub>GS(th)</sub>              | $V_{DS} = V_{GS}$ , $I_{D} = 250 \mu\text{A}$  | 1.0  |       | 3.0   | V           |  |
| Gate-Source Leakage                           | I <sub>GSS</sub>                 | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$  |      |       | ± 100 | nA          |  |
| Zara Oata Waltana Brain Oarrani               | I <sub>DSS</sub>                 | V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V  |      |       | 1     |             |  |
| Zero Gate Voltage Drain Current               |                                  | V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C                      |      |       | 10    | μA          |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>               | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$  | 30   |       |       | Α           |  |
|   | <b>D</b>                         | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A  |      | 13    |       | mΩ          |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>              | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A   |      | 19    |       |             |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>                  | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A  |      | 75    |       | S           |  |
| Dynamic <sup>b</sup>                          |                                  |  |      | l     |       |             |  |
| Input Capacitance                             | C <sub>iss</sub>                 |  |      |       | 900   | pF          |  |
| Output Capacitance                            | C <sub>oss</sub>                 | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$                           |      |       | 236   |             |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>                 |  |      |       | 20    |             |  |
|   |                                  | V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A                      |      |       | 20    |             |  |
|   |                                  |  |      | 9     |       |             |  |
| Gate-Source Charge                            | $Q_{gs}$                         | $V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$                      |      |       | 2.1   | nC          |  |
| Gate-Drain Charge                             | Q <sub>gd</sub>                  | 1  |      |       | 0.7   |             |  |
| Gate Resistance                               | R <sub>g</sub>                   | f = 1 MHz  | 0.2  | 1.1   | 2.2   | Ω           |  |
| Turn-On Delay Time                            | t <sub>d(on)</sub>               |  |      | 8     | 16    |             |  |
| Rise Time                                     | t <sub>r</sub>                   | $V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$  |      | 16    | 30    |             |  |
| Turn-Off Delay Time                           | t <sub>d(off)</sub>              | $I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$                          |      | 17    | 35    |             |  |
| Fall Time                                     | t <sub>f</sub>                   | 1  |      | 7     | 15    |             |  |
| Turn-On Delay Time                            | t <sub>d(on)</sub>               |  |      | 14    | 30    | ns          |  |
| Rise Time                                     | t <sub>r</sub>                   | $V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$  |      | 50    | 100   | -<br>-<br>- |  |
| Turn-Off Delay Time                           | t <sub>d(off)</sub>              | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$                           |      | 16    | 30    |             |  |
| Fall Time                                     | t <sub>f</sub>                   | ]  |      | 8     | 18    |             |  |
| Drain-Source Body Diode Characteristi         | cs                               |  |      |       |       |             |  |
| Continuous Source-Drain Diode Current         | I <sub>S</sub>                   | T <sub>C</sub> = 25 °C   |      |       | 13    |             |  |
| Pulse Diode Forward Current <sup>a</sup>      | I <sub>SM</sub>                  |  |      |       | 100   | Α           |  |
| Body Diode Voltage                            | V <sub>SD</sub>                  | I <sub>S</sub> = 3 A   |      |       | 1.2   | V           |  |
| Body Diode Reverse Recovery Time              | t <sub>rr</sub>                  |  |      |       | 40    | ns          |  |
| Body Diode Reverse Recovery Charge            | Q <sub>rr</sub>                  | 1 _ 10 A dl/dt _ 100 A/vs T _ 05 °C  |      |       | 20    | nC          |  |
| Reverse Recovery Fall Time                    | t <sub>a</sub>                   | $I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ |      | 12.5  |       |             |  |
| Reverse Recovery Rise Time                    | t <sub>b</sub>                   |  |      | 7.5   |       | ns          |  |

## Notes:

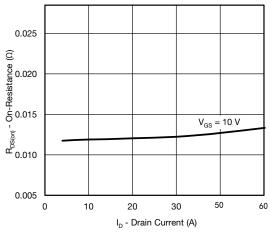
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

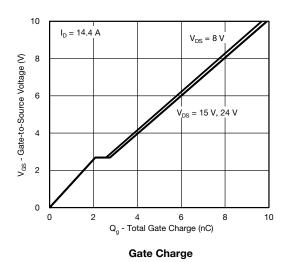


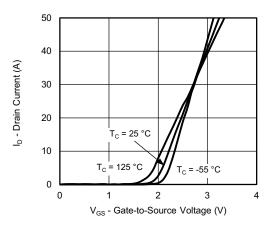


## **Output Characteristics**

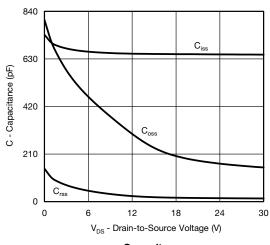


On-Resistance vs. Drain Current

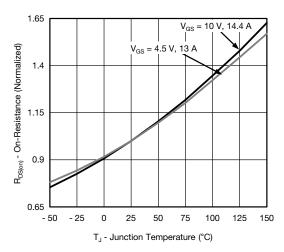




**Transfer Characteristics** 

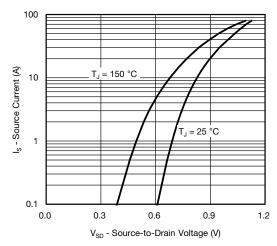


Capacitance

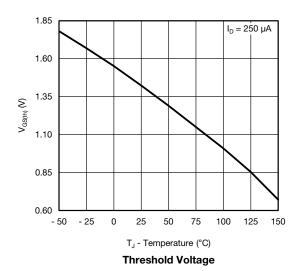


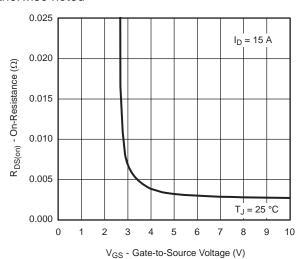
On-Resistance vs. Junction Temperature



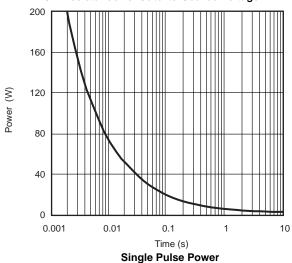


#### **Source-Drain Diode Forward Voltage**





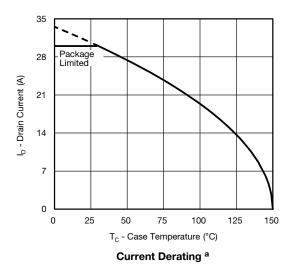
On-Resistance vs. Gate-to-Source Voltage

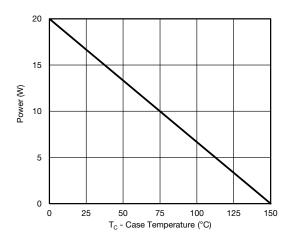


 $(3) \begin{array}{c} 100 \\ \text{Limited by } P_{\text{Oscion}} \\ 10 \\ \text{Limited by } P_{\text{Oscion}} \\ 1 \\ \text{O.01} \\ \text{O.1} \\ \text{O.1} \\ \text{O.1} \\ \text{O.1} \\ \text{O.2} \\ \text{O.2} \\ \text{O.3} \\ \text{O.2} \\ \text{O.3} \\ \text{O.3} \\ \text{O.4} \\ \text{O.5} \\ \text{O.5} \\ \text{O.6} \\ \text{O.7} \\ \text{O.8} \\ \text{O.8} \\ \text{O.9} \\ \text{O.$ 

Safe Operating Area, Junction-to-Ambient





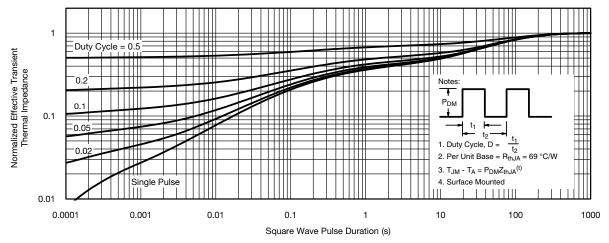


Power, Junction-to-Case

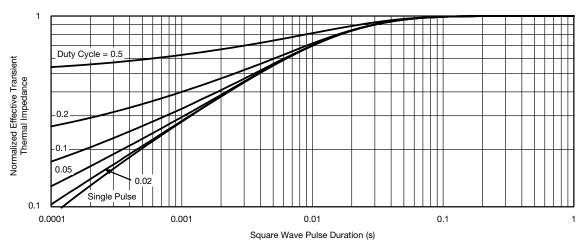
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



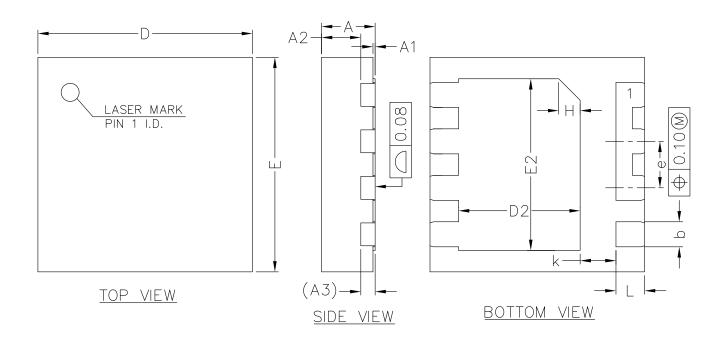


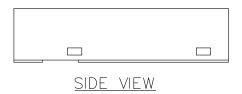
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case







COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

| SYMBOL | MIN     | NOM  | MAX  |  |
|--------|---------|------|------|--|
| Α      | 0.70    | 0.75 | 0.80 |  |
| A1     | 0.00    | 0.02 | 0.05 |  |
| A2     | 0.50    | 0.55 | 0.60 |  |
| A3     | 0.20REF |      |      |  |
| b      | 0.30    | 0.35 | 0.40 |  |
| D      | 2.90    | 3.00 | 3.10 |  |
| Е      | 2.90    | 3.00 | 3.10 |  |
| D2     | 1.60    | 1.70 | 1.80 |  |
| E2     | 2.30    | 2.40 | 2.50 |  |
| е      | 0.55    | 0.65 | 0.75 |  |
| K      | 0.40    | 0.50 | 0.60 |  |
| L      | 0.35    | 0.40 | 0.45 |  |



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